

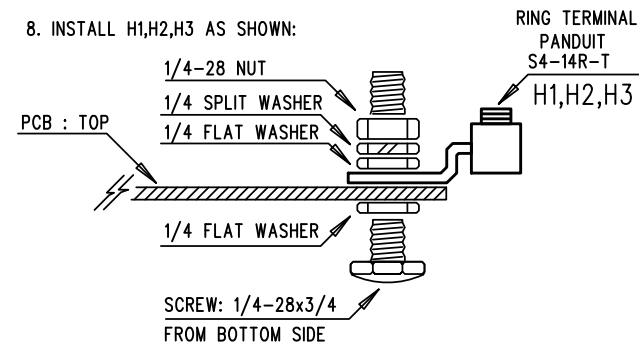
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	4	PRODUCTION	MANPREET S.	07-29-19

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL DLED1-DLED8 AS SHOWN:



8. INSTALL H1,H2,H3 AS SHOWN:



APPROVALS		ANALOG DEVICES POWER BY LINEAR		
PCB DES.	KIM T.	www.analog.com 2555 AUGUSTINE DRIVE, SANTA CLARA, CA 95054		
APP ENG.	MANPREET S.	TITLE: TOP ASSEMBLY DRAWING HIGH POWER PARALLEL MODE -48V HOT SWAP CONTROLLER WITH TELEMETRY AND EEPROM		
		SIZE	IC NO.	REV.
		N/A	LTC4284IUHG DEMO CIRCUIT 2909A	4
SCALE = NONE		FILENAME: DC2909A-4.PCB		SHT 1 OF 2